

Title (en)  
TERMINAL ELEMENT OR BUS BAR, AND POWER SEMICONDUCTOR MODULE ARRANGEMENT COMPRISING A TERMINAL ELEMENT OR BUS BAR

Title (de)  
ANSCHLUSSELEMENT ODER SAMMELSCHIENE UND LEISTUNGSHALBLEITERMODULANORDNUNG MIT EINEM ANSCHLUSSELEMENT ODER EINER SAMMELSCHIENE

Title (fr)  
ÉLÉMENT TERMINAL OU BARRE DE BUS ET AGENCEMENT DE MODULE D'ALIMENTATION À SEMI-CONDUCTEUR COMPRENANT UN ÉLÉMENT TERMINAL OU UNE BARRE DE BUS

Publication  
**EP 4187595 A1 20230531 (EN)**

Application  
**EP 21211006 A 20211129**

Priority  
EP 21211006 A 20211129

Abstract (en)  
A terminal element or bus bar for a power semiconductor module arrangement comprises a first end configured to be arranged inside a housing of the power semiconductor module arrangement, a second end configured to be arranged outside of the housing of the power semiconductor module arrangement, and at least a first section and a second section arranged successively between the first end and the second end along a length of the terminal element or bus bar, wherein either the first section comprises a first material, the second section comprises a second material, and the first material differs from the second material, or the first section has a first thickness, the second section has a second thickness, and the first thickness differs from the second thickness, or both.

IPC 8 full level  
**H01L 23/498** (2006.01); **H01L 23/053** (2006.01)

CPC (source: CN EP US)  
**H01L 21/4842** (2013.01 - US); **H01L 21/4846** (2013.01 - CN); **H01L 21/4853** (2013.01 - CN); **H01L 23/053** (2013.01 - EP US); **H01L 23/24** (2013.01 - EP); **H01L 23/488** (2013.01 - CN); **H01L 23/49** (2013.01 - CN); **H01L 23/49811** (2013.01 - EP US); **H01L 23/5383** (2013.01 - US); **H01L 25/072** (2013.01 - US); **H01L 25/18** (2013.01 - US); **H01L 24/29** (2013.01 - US); **H01L 24/32** (2013.01 - US); **H01L 24/48** (2013.01 - US); **H01L 24/73** (2013.01 - US); **H01L 2224/29139** (2013.01 - US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/32238** (2013.01 - EP); **H01L 2224/48225** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - US)

Citation (search report)

- [X] US 2016247735 A1 20160825 - LIN YUSHENG [US], et al
- [X] US 2017170083 A1 20170615 - YAO YUSHUANG [MY], et al
- [X] US 2017170084 A1 20170615 - YAO YUSHUANG [MY], et al

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

Designated validation state (EPC)  
KH MA MD TN

DOCDB simple family (publication)  
**EP 4187595 A1 20230531**; CN 116190339 A 20230530; US 2023170286 A1 20230601

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**EP 21211006 A 20211129**; CN 202211520618 A 20221129; US 202218070092 A 20221128